Assembly Research Consortium to Meet on Process and Reliability Issues

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OWEGO, NY – The Advanced Research in Electronics Assembly Consortium will gather Feb. 27-28 to review this year's research plan and to review results of recent investigations.

Attendees from more than 30 companies and institutions are expected to attend the two-day workshop in Owego for an in-depth look at process and reliability-related research in electronics assembly.

During the workshop, Unovis researchers will review their 2007 findings pertaining to the consortium's research tracks. Progress reports will highlight development in the consortium's lead-free studies. Reliability issues pertaining to surface finishes, underfilling and repair will also be discussed. Also, recent investigations on TSV stacking will be presented.